Preface

This volume is the compilation of the accepted proceedings which were submitted to the 12th European Conference on Silicon Carbide and Related Materials 2018 (ECSCRM 2018) held in Birmingham, UK from 2nd - 6th September. ECSCRM, alongside its sister conference ICSCRM, provides a vibrant scientific forum in which recent issues relating to silicon carbide and other wide bandgap materials, including gallium nitride, gallium oxide and graphene, can be discussed. We hope the attendees as much as we enjoyed organising and hosting it.

ECSCRM 2018 was attended by 660 people from over 30 countries, including experienced researchers and their students, and experts from leading companies. The attendance to ECSCRM continues to grow, with a notable increase in participation from industry. This is testament to the continued maturity of wide bandgap semiconductor technologies, and its adoption within a diverse mix of technology areas. In addition 46 companies and organisations were exhibitors or sponsors, showing the strong industrial interest and support for silicon carbide and associated technologies.

There were 99 oral and 220 poster presentations within the four days of ECSCRM 2018, including 15 invited presentations and 3 plenary talks. These contributions spanned the wide range of topics being worked on in the field of SiC and related semiconductor materials. The present book contains selected proceedings distributed among 5 main topics; Bulk and Epitaxial Growth, Characterisation, Processing, Devices and Applications.

We wish to thank all the contributors to this volume, both authors and reviewers, for their efforts to submit and correct high quality papers on time and in copy-ready format. We are extremely grateful for the work of the Technical Programme Committee for their valuable efforts to ensure the high scientific quality of the conference programme, while the International Steering Committee provided valuable guidance.

The success of ECSCRM 2018 is the result of the dedication and hard work of many people. However, we would like to express our sincere gratitude to Faye Padfield for her Herculean efforts in supporting, organising and managing all elements of ECSCRM 2018 over the last 2 years. Without Faye, the conference would not have run so smoothly or been as successful. We would also like to thank the local organising teams of the University of Warwick and colleagues from the Universities of Nottingham and Newcastle.

Sponsors, exhibitors and media partners of the conference are much thanked for their financial and promotional support, which is essential for the success of the conference series.

The next conference of this series will be held in Tours, France in September 2020 chaired by Professor Daniel Alquier (GREMAN, Tours); Dr Jean-François Michaud (GREMAN, Tours) Professor Dominique Planson (AMPERE, Lyon) and Dr Luong Viet Phung (AMPERE, Lyon).

Birmingham, UK – March 2019

Professor Phil Mawby, Chairperson ECSCRM 2018
Dr Peter Gammon, Technical Programme Chair ECSCRM 2018

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